

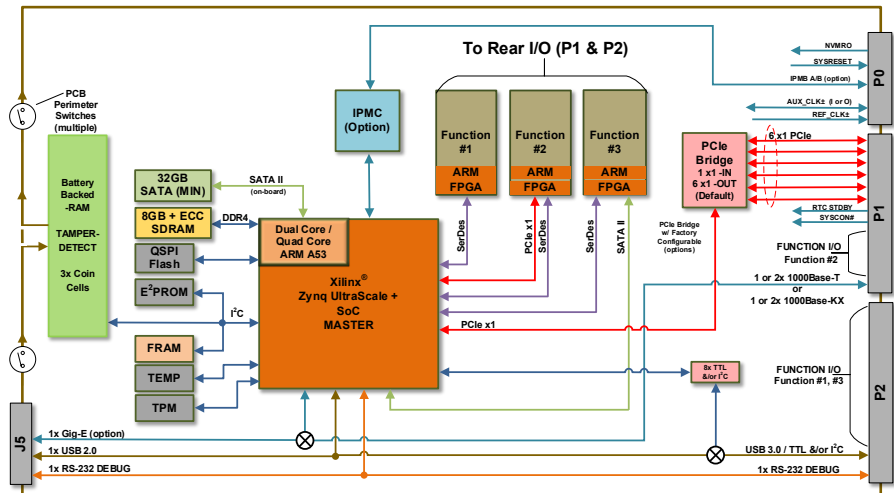


## 68ARM2 3U OpenVPX™ SBC with Three Smart I/O Function Module Slots

*Over 70 different functions to choose from*

### Configure to Customize

The **68ARM2** is a 3U OpenVPX Zynq® UltraScale+™ Quad-core ARM® Cortex™-A53 MPCore™ based Single Board Computer that can be configured with up to three NAI Smart I/O and communications function modules. Ideally suited for rugged Mil-Aero applications, the 68ARM2 delivers off-the-shelf solutions that accelerate deployment of SWaP-optimized systems in air, land and sea applications.



## Features Summary

- **3U OpenVPX (ANSI/VITA 65)**  
Profiles Supported:
  - MOD3-PAY-1F2U-16.2.11-2
    - Data plane: 6 x1 PCIe (default) (other factory configurations avail.)
    - Control plane: 2x 10/100/1000Base-T or 2x 1000Base-KX
  - SLT3-PAY-1F2U-14.2.12
- **Processor/Memory**
  - Xilinx Zynq® UltraScale+™ Quad-core ARM® Cortex™-A53 MPCore™ up to 1.3 GHz
  - 8 GB DDR4 SDRAM w/ ECC
  - 32 GB SATA II NAND Flash
- **Smart I/O Functions**
  - Support for 3 independent modules
  - PCIe interface to function slot #2 (e.g. for 2 additional Gig-E ports option)
  - SATA II interface to function slot #3 (e.g. for 256 GB expansion option)
- **Security / Cybersecurity (Option)**
  - FIPS 140-3 Level 3 Design Support
  - Crypto-key storage
    - Battery-backed RAM
  - Secure Boot
  - Anti-tamper / Tamper Detect & Sanitize
- **Motherboard Peripheral I/O:**
  - USB 2.0 to front maintenance J5 (option)
  - USB 3.0 to rear I/O (option)
  - I²C Bus to rear I/O (option)
  - 1x RS232 console port
    - To front maintenance J5 & rear I/O
  - 2x TTL I/O to rear I/O (8x TTL option)
- **IPMC Support**
  - VITA 46.11 Tier-2, basic, compatible (configured option)
- **Power**
  - < 15 W power dissipation (est./typ.) (not including module power)
- **Operating Systems**
  - Xilinx PetaLinux
  - Wind River® VxWorks®
  - DDC-I Deos
- **Background Built-in-Test**  
Continuous BIT (as applicable)
- **COSA® Architecture**
- **Intelligent I/O library support** (included)
- **VICTORY Interface Services** (Contact factory)
- **Commercial or Rugged Applications**
- **Operating Temperature**
  - Commercial: 0°C to 70°C
  - Rugged: -40°C to 85°C
- **Mechanical Options (ANSI/VITA 48)**
  - Air-cooled; 3U, 5HP/1.0" pitch
  - Conduction-cooled; 3U, 1.0" pitch

### Select up to 3 functions for your application

For a full listing of available smart functions and detailed specifications please visit <https://www.naii.com/functions>

Analog & Digital I/O							
Function	Module	Description		Function	Module	Description	
A/D Converter	AD1	12 Ch. $\pm 1.25$ to $\pm 10.0$ VDC FSR; 256 kHz (max), 24-bit Sigma-Delta		D/A Converter	DA1	12 Ch. $\pm 10$ VDC or $\pm 25$ mA / Ch.	
	AD2	12 Ch. $\pm 12.5$ to $\pm 100.0$ VDC FSR; 256 kHz (max), 24-bit Sigma-Delta			DA2	16 Ch. $\pm 10$ VDC @ 10 mA max. / Ch.	
	AD3	12 Ch. $\pm 25$ mA FSR; 24-bit 256 kHz (max), Sigma-Delta			DA3	4 Ch. $\pm 40$ VDC or $\pm 100$ mA / Ch.	
	AD4	16 Ch. $\pm 1.25$ to $\pm 10.0$ VDC FSR or $\pm 25$ mA; 16-bit SAR, 8 Ch. x 2 A/D multiplexed, 400 kHz (aggregate per A/D)			DA4	4 Ch. $\pm 20$ to $\pm 80$ VDC @ $\pm 10$ mA max. / Ch.	
	AD5	16 Ch. $\pm 6.25$ to $\pm 50.0$ VDC FSR; 16-bit SAR, 8 Ch. x 2 A/D multiplexed, 400 kHz (aggregate per A/D)			DA5	2 Ch. 65 VDC @ $\pm 2$ A max., external applied VCC source	
	AD6	16 Ch. $\pm 12.5$ to $\pm 100.0$ VDC FSR; 16-bit SAR, 8 Ch. x 2 A/D multiplexed, 400 kHz (aggregate per A/D)		I/O Discrete	DT1	24 Ch. Discrete I/O, 0 - 60 VDC, 500 mA / Ch. max.	
	ADE	16 Ch. $\pm 10$ VDC FSR; 200 kHz (max.), 16-bit SAR			DT2	16 Ch. Discrete switch, $\pm 80$ V, 625 mA / Ch. max., isolated	
	ADF	16 Ch. $\pm 100$ VDC FSR; 200 kHz (max.), 16-bit SAR			DT3	4 Ch. Discrete-switch, 65 V, 2 A / Ch. as half-bridge configuration, ext. VCC or 2 Ch. $\pm 65$ V, 2 A / Ch. as full-bridge configuration, ext. VCC	
	ADG	16 Ch. $\pm 25$ mA FSR; 200 kHz (max.), 16-bit SAR			DT4	24 Ch. Discrete I/O, 0 - 60 VDC, 500 mA / Ch. max., enhanced operation	
		DT5			16 Ch. Discrete switch, $\pm 80$ V, 625 mA / Ch., enhanced operation		
I/O TTL/CMOS	TL1	24 Ch. 3.3V/5V tolerant, high-speed, programmable		DT6	4 Ch. Discrete-switch, 65 V, 2 A / Ch. as half-bridge configuration, ext. VCC or 2 Ch. $\pm 65$ V, 2 A / Ch. as full-bridge configuration, ext. VCC (DT3-type enhanced operation TBD/pending)		
	TL2	24 Ch. 3.3V/5V tolerant, high-speed, programmable, enhanced					
	TL3 – TL8	24 Ch. 3.3V/5V tolerant, multiple strapping options			I/O Relay	RY1	4 Ch. SPDT, 220 VDC/ 250 VAC, 2 A, 60 W/62.5 VA max., non-latching
I/O Differential	DF1	16 Ch. RS-422/485 I/O transceiver		RY2		4 Ch. SPDT, 220 VDC/ 250 VAC, 2 A, 60 W/62.5 VA max., latching	
	DF2	16 Ch. RS-422/485 I/O transceiver, enhanced					
Position, Timing, Measurement & Simulation							
Function	Module	Description			Function	Module	Description
AC Reference	AC1	1 Ch. 2-28 Vrms (LV) & 1 Ch. 28-115 Vrms (HV), programmable			SYN/RSL-to-Dig	SD1	4 Ch. 2-28 Vrms Input, 2-115 Vrms Exc, 47 Hz - 1 Hz Freq
	AC2	2 Ch. 2-28 Vrms (LV), 47 Hz -20 kHz (max. range),	SD2			4 Ch. 2-28 Vrms Input, 2-115 Vrms Exc, 1 kHz - 5 kHz Freq	
	AC3	2 Ch. 28-115 Vrms (HV), 47 Hz - 2.5 kHz (max. range)	SD3			4 Ch. 2-28 Vrms Input, 2-115 Vrms Exc, 5 kHz - 10 kHz Freq	
Thermocouple (Measure)	TC1	8 Ch. Thermocouple, J, K, T, E, N, B, R, S, and Low-voltage A/D	SD4			4 Ch. 2-28 Vrms Input, 2-115 Vrms Exc, 10 kHz - 20 kHz Freq	
	TR1	8 Ch. RTD (RT1-type) or Thermocouple (TC1-type), programmable per Ch.	SD5			4 Ch. 28-90 Vrms Input, 2-115 Vrms Exc, 47 Hz - 1 kHz Freq	
	RT1	8 Ch. RTD (2,3 or 4 wire), standard PT-type to 4 kohm					
GPS	GP1	Multi-Ch. (satellite) GPS & IRIG Receiver or Source; 2x wide module, Javad TR2 high-performance GPS engine	L(R)VDT-to-Dig	LD1-5	4 Ch. 2-28 Vrms Input, 2-115 Vrms Exc (47 Hz - 20 kHz Freq. and 2-90 Vrms ranges, reference detailed specifications)		
	GP2	Multi-Ch. (satellite) GPS & IRIG Receiver or Source; 1x wide module, uBlox Neo GPS engine		Dig-to-SYN/RSL Dig-to-L(R)VDT	DSx / DRx DLx	3, 2 or 1 Ch. @ 0.5 VA, 2.2 VA or 3.0 VA 2-90 Vrms / 2-115 Vexc @ 47 Hz – 20 kHz (Multi-range inputs/frequency; reference module detailed specifications)	
IRIG	RG1	1 Ch. IRIG Receiver or Source, digital & analog w/ master timer	Chip Detect	CD1	Six (6) chip detection and burn channels		
Strain Gauge	SG1	4 Ch. Strain Gauge, full-bridge measurement	Variable Reluctance	VR1	8 Channels, Differential Input		

### Select up to 3 functions for your application (Continued)

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Communication						
Function	Module	Description		Function	Module	Description
ARINC	AR1	12 Ch. ARINC 429/575, TX or RX		CANBus	CB1	8 Ch. CAN bus, CAN 2.0 A/B Protocol
	AR2	1 Ch. ARINC 568 (TX & RX) & 1 Ch. ARINC 579 (TX or RX)			CB2	8 Ch. CAN bus, J1939 Protocol
MIL-STD-1553	FTA, FTB, FTC	1, 2 & 4 Ch. MIL-STD-1553, Dual Redundant XFMR-Coupled Assisted Mode Capable			CB3	8 Ch. CAN bus, CAN 2.0 A/B Protocol or J1939 Protocol, programmable
	FTD, FTE, FTF	1, 2 & 4 Ch. MIL-STD-1553, Dual Redundant Direct-Coupled Assisted Mode Capable		Serial	SC1	4 Ch. Serial Communications, multi-mode RS-232/422/485/423 capable, ASYNC/SYNC (S/HDLC) non-isolated
MIL-STD-1760	FTJ	1 Ch. MIL-STD-1553/1760, XFMR-Coupled			SC2	4 Ch. Serial Communications, multi-mode programmable, isolated
	FTK	2 Ch. MIL-STD-1553/1760 XFMR-Coupled			SC3	8 Ch. Serial Communications RS-232/422/485 or GPIO, non-isolated
Ethernet	EM1	2-Port 10/100/1000Base-T Ethernet NIC, Intel 82850, PCIe I/F to processor (local or off-board host)			SC7	4 Ch. Serial Communications, multi-mode, individual GNDs, non-isolated
	ES2	16-Port 10/100/1000Base-T, managed switch, with L2/L3 Layer support 4x 10Gb Fiber Optic option, 2x wide module				
Combination & Specialty						
Function	Module	Description			Function	Module
Combination	CM5	2 Ch. MIL-STD-1553 & 8 Ch. ARINC 429/575		Flash	FM1	240 GB SSD, SATA II, MLC, -40° C to +85° C
	CM8	2 Ch. MIL-STD-1553 & 12 Ch. Discrete I/O			FM2	480 GB SSD, SATA II, MLC, -40° C to +85° C
					FM4	128 GB SSD, SATA II, SLC, -40° C to +85° C
					FM5	256 GB SSD, SATA II, SLC, -40° C to +85° C
					FM7	1 TB SSD, SATA II, TLC, 0° C to +70° C
					FM8	1 TB SSD, SATA II, TLC, -40° C to +85° C
					FM9	2 TB SSD, SATA II, TLC, -40° C to +85° C

### Architected for Versatility

NAI's Configurable Open System Architecture™ (COSA®) offers a choice of over 70 smart I/O, communications, or Ethernet switch functions, providing the highest packaging density and greatest flexibility of any 3U SBC in the industry. Preexisting, fully-tested functions can be combined in an unlimited number of ways quickly and easily.

### Board Support Package and Software Support

The 68ARM2 includes BSP and SDK support for Xilinx PetaLinux or Wind River® VxWorks®. Please contact the factory regarding other OS support (e.g. DDC-I Deos, etc.). In addition, software support kits are supplied, with source code and board-specific library I/O APIs, to facilitate system integration. Each I/O function has dedicated processing, unburdening the SBC from unnecessary data management overhead.

### Background Built-In-Test (BIT)

BIT continuously monitors the status of all I/O during normal operations and is totally transparent to the user. SBC resources are not consumed while executing BIT routines. This simplifies maintenance, assures operational readiness, reduces life-cycle costs and - *keeps your systems mission ready.*

### One-Source Efficiencies

Eliminate man-months of integration with a configured, field-proven system from NAI. Specification to deployment is a seamless experience as all design, state-of-the-art manufacturing, assembly and test are performed - by one trusted source. All facilities are located within the U.S. and optimized for high-mix/low volume production runs and extended lifecycle support.

### Product Lifecycle Management

From design to production and beyond, NAI's product lifecycle management strategy ensures the long-term availability of COTS products through configuration management, technology refresh and obsolescence component purchase and storage



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